

Electronic Patent Application Fee Transmittal

Application Number:	10588024			
Filing Date:	31-May-2007			
Title of Invention:	Repair Soldering Method for Repairing a Component Which Comprises a Base Material with an Oriented Microstructure			
First Named Inventor/Applicant Name:	Dirk Goldschmidt			
Filer:	Ye Ren/Ann Hickey			
Attorney Docket Number:	2003P18131WOUS			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				810